



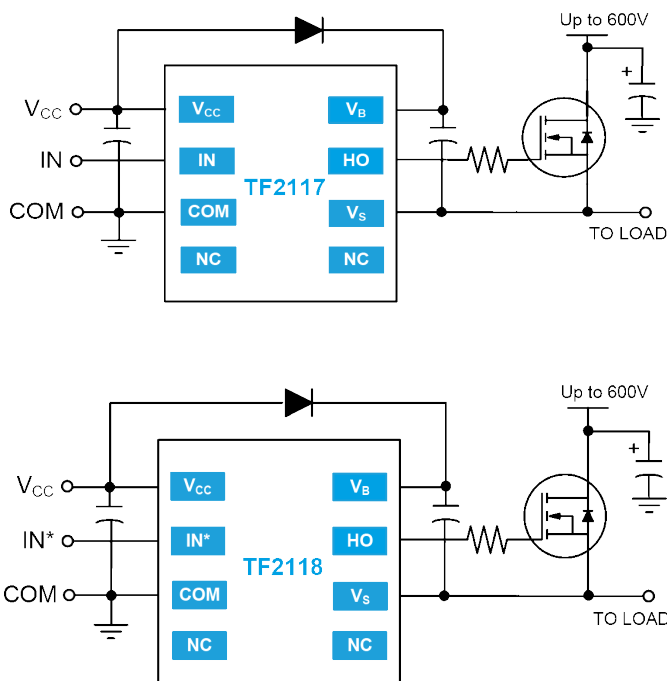
Features

- Floating channel in bootstrap operation to 600V
- Drives one N-channel MOSFET or IGBT
- Outputs tolerant to negative transients
- Wide logic supply: 10V to 20V
- Schmitt triggered logic input with internal pull down
- Undervoltage lockout
- Extended temperature range: -40°C to +125°C

Applications

- DC-DC Converters
- AC-DC Inverters
- Motor Controls
- Class D Power Amplifiers

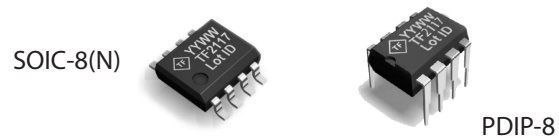
Typical Application



Description

The TF2117 and TF2118 are high voltage, high speed gate drivers capable of driving one N-channel MOSFETs and IGBTs in a bootstrap operation. Telefunken's high voltage process enables the TF2117 and TF2118 to switch at 600V. The TF2117 and TF2118 logic input is compatible with standard CMOS outputs. The driver output features high pulse current buffers designed for minimum driver cross conduction. The single floating channel can be used in high side or low side configuration.

The TF2117 and TF2118 are offered in a space saving 8-pin SOIC and 8-pin PDIP package. They operate over an extended -40 °C to +125 °C temperature range.

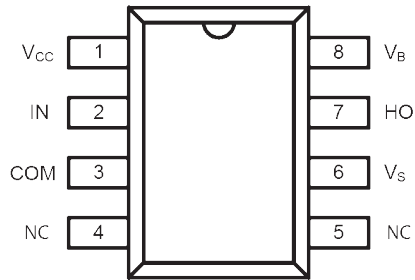
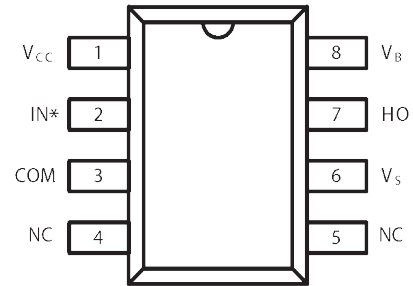


Ordering Information

Year Year Week Week

PART NUMBER	PACKAGE	PACK / Qty	MARK
TF2117-TEU	SOIC-8	Tube / 100	 YYWW TF2117 Lot ID
TF2117-TEQ		T&R / 2500	
TF2117-3AS	PDIP-8	Tube / 50	 YYWW TF2117 Lot ID
TF2118-TEU	SOIC-8	Tube / 100	 YYWW TF2118 Lot ID
TF2118-TEQ		T&R / 2500	
TF2118-3AS	PDIP-8	Tube / 50	 YYWW TF2118 Lot ID

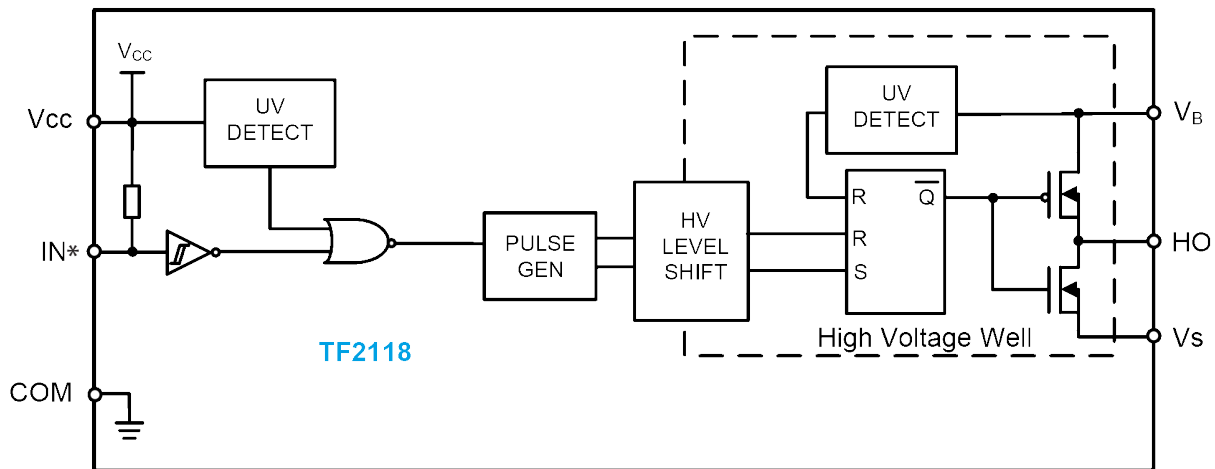
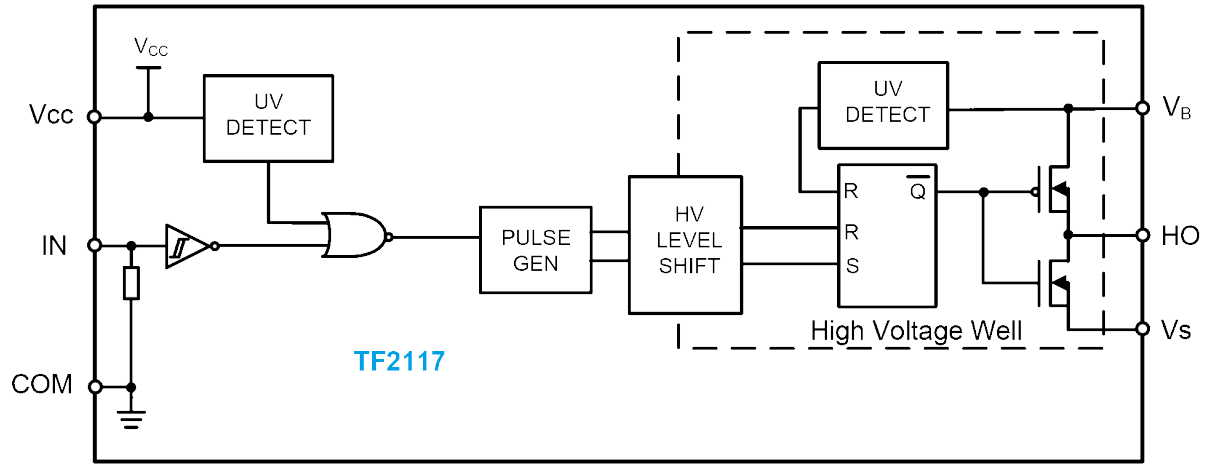
Pin Diagrams


Top View: PDIP-8, SOIC-8
TF2117

Top View: PDIP-8, SOIC-8
TF2118

Pin Descriptions

PIN NAME	PIN DESCRIPTION
VCC	Logic and gate drive supply
IN	TF2117 Logic input for gate driver output (HO), in phase with HO
IN*	TF2118 Logic input for gate driver output (HO), out of phase with HO
COM	Logic ground
NC	No Connect
V_S	High-side floating supply return
HO	High-side gate drive output
V_B	High-side floating supply

Functional Block Diagram



Absolute Maximum Ratings (NOTE1)

V_B - High side floating supply voltage.....-0.3V to +624V
 V_S - High side floating supply offset voltage... V_B -24V to V_B +0.3V
 V_{HO} - High side floating output voltage..... V_S -0.3V to V_B +0.3V
 V_{CC} - Logic supply voltage.....-0.3V to +24V
 V_{IN} - Logic input voltage.....-0.3V to V_{CC} +0.3V
 dV_S / dt - Allowable offset supply voltage transient.....50 V/ns

P_D - Package power dissipation at $T_A \leq 25^\circ\text{C}$
 SOIC-8.....0.625W
 PDIP-8.....1.0W
 $R_{\theta JA}$ - Thermal Resistance, junction to Ambient
 SOIC-8.....200°C/W
 PDIP-8.....200°C/W

NOTE1 Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

T_J - Junction temperature.....+150 °C
 T_S - Storage temperature-55 to 150 °C
 T_L - Lead Temperature (soldering, 10 seconds.....300 °C

SOIC-8 Thermal Resistance (NOTE2)

θ_{JC}45 °C/W
 θ_{JA}200 °C/W

PDIP-8 Thermal Resistance (NOTE2)

θ_{JC}35 °C/W
 θ_{JA}125 °C/W

NOTE2 When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Symbol	Parameter	MIN	TYP	MAX	Unit
V_B	High side floating supply absolute voltage	$V_S + 10$		$V_S + 20$	V
V_S	High side floating supply offset voltage	NOTE3		600	
V_{HO}	High side floating output voltage	V_S		V_B	
V_{CC}	Low side and logic fixed supply voltage	10		20	
V_{IN}	Logic input voltage (HIN and LIN)	0		V_{CC}	
T_A	Ambient temperature	-40		125	°C

NOTE3 Logic operational for VS of -5V to +600V. Logic state held for VS of -5V to -VBS

DC Electrical Characteristics (NOTE4)

$V_{BIAS} (V_{CC}, V_{BS}) = 15V, T_A = 25^\circ C$, unless otherwise specified.

Symbol	Parameter	Conditions	MIN	TYP	MAX	Unit
V_{IH}	Logic "1" input voltage		9.5			V
V_{IL}	Logic "0" input voltage				6.0	
V_{OH}	High level output voltage, $V_{BIAS} - V_O$	$I_O = 2mA$		0.05	0.2	
V_{OL}	Low level output voltage, V_O	$I_O = 2mA$		0.02	0.1	
I_{LK}	Offset supply leakage current	$V_B = V_S = 600V$			50	μA
I_{BSQ}	Quiescent V_{BS} supply current	$V_{IN} = 0V$ or V_{CC}		50	240	
I_{CCQ}	Quiescent V_{CC} supply current	$V_{IN} = 0V$ or V_{CC}		70	340	
I_{IN+}	Logic "1" input bias current	$V_{IN} = V_{CC}$		20	40	
I_{IN-}	Logic "0" input bias current	$V_{IN} = 0V$			5.0	V
V_{BSUV+}	V_{BS} supply under-voltage positive going threshold		7.6	8.6	9.6	
V_{BSUV-}	V_{BS} supply under-voltage negative going threshold		7.2	8.2	9.2	
V_{CCUV+}	V_{CC} supply under-voltage positive going threshold		7.6	8.6	9.6	
V_{CCUV-}	V_{CC} supply under-voltage negative going threshold		7.2	8.2	9.2	mA
I_{O+}	Output high short circuit pulsed current	$V_O = 0V, V_{IN} = \text{Logic "1"}, PW \leq 10 \mu s$	200	290		
I_{O-}	Output low short circuit pulsed current	$V_O = 15V, V_{IN} = \text{Logic "0"}, PW \leq 10 \mu s$	420	600		

AC Electrical Characteristics

$V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF$, and $T_A = 25^\circ C$, unless otherwise specified.

Symbol	Parameter	Conditions	MIN	TYP	MAX	Unit
t_{ON}	Turn-on propagation delay	$V_S = 0V$		125	200	ns
t_{OFF}	Turn-off propagation delay	$V_S = 600V$		105	180	
t_r	Turn-on rise time			75	130	
t_f	Turn-off fall time			35	65	

NOTE4 The V_{IH} , V_{TH} and I_{IN} parameters are referenced to COM and are applicable to all three logic input pins: HIN, LIN and SD. The V_O and I_O parameters are referenced to COM and are applicable to the respective output pins: HO and LO.

Timing Waveforms

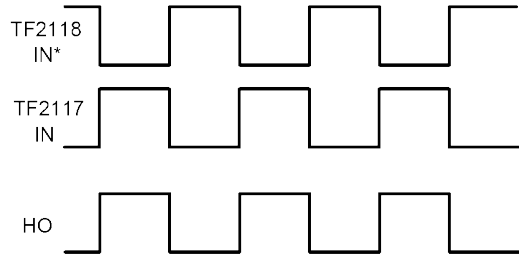


Figure 1. Input / Output Timing Diagram

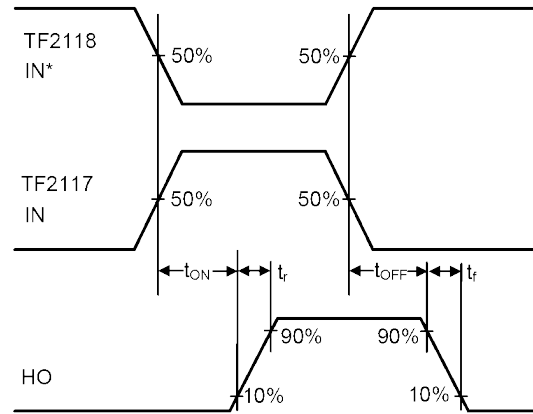
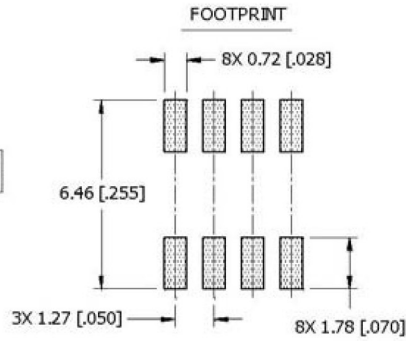
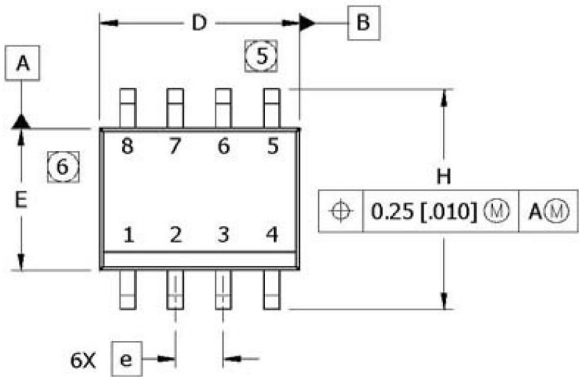


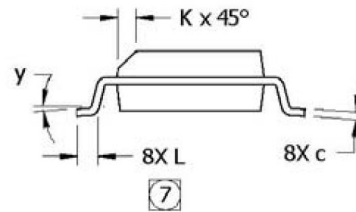
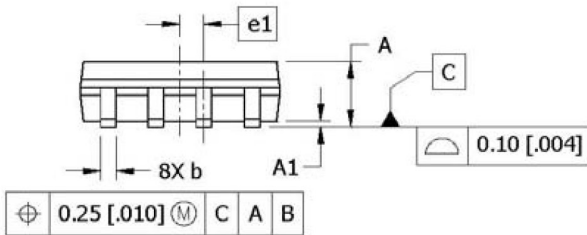
Figure 2. Switching Time Waveform Definitions

Package Dimensions (SOIC-8 N)

Please contact support@tfsemi.com for package availability.



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°



NOTES:

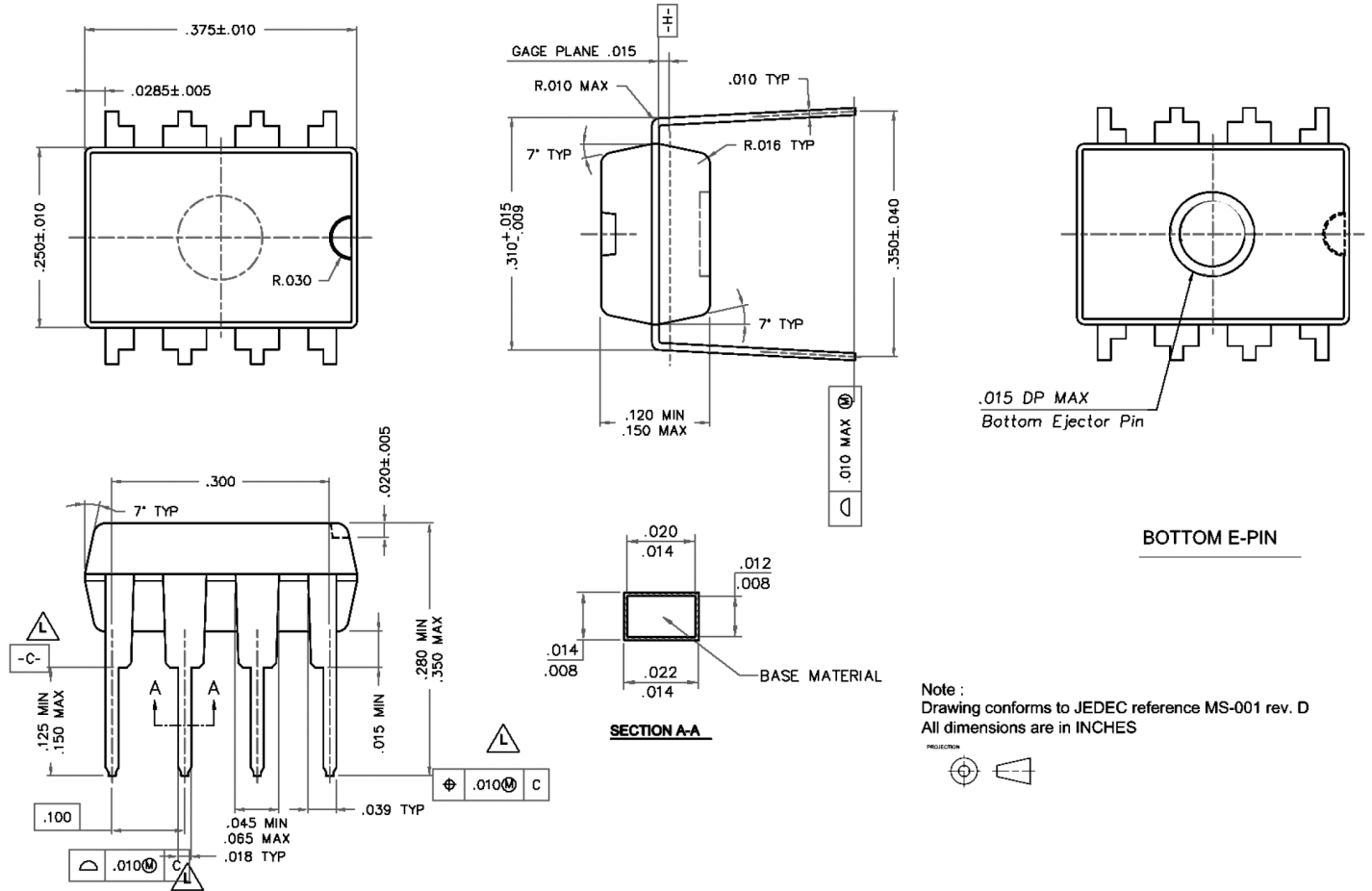
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.

5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 [0.006].
6. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 [0.010].
7. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

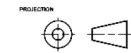
01-6027

Package Dimensions (PDIP-8)

Please contact support@tfsemi.com for package availability.



Note :
Drawing conforms to JEDEC reference MS-001 rev. D
All dimensions are in INCHES



Notes

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